• Specifications

MOOV

Applicable Wafer size		Circular wafer : ϕ8" to ϕ12"
X-axis	Stroke	550mm
	Cutting feed rete	0.1mm to 600mm/s
	Positioning resolution	0.002mm
	Straightness	0.0015mm/310mm(both horizontal and vertical)
Y-axis	Stroke	427mm
	Driving speed	max.80mm/s
	Positioning resolution	0.0002mm(closed-loop control)
	Positioning accracy	0.002mm/310mm
Z-axis	Stroke	8.5mm
	Driving speed	max.10mm/s
	Positioning resolution	0.0001mm(closed-loop control)
	Positioning accracy	0.001mm/1mm

• Others

Power supply	Supply voltage : Selected from 200/220/240/380/415 VAC ± 10% 3 phase, 50 to 60 Hz.
Power consumption	7kVA max
Copressed air	Pressure : 0.5 to 0.7 MPa
N2 gas	Pressure : 0.5 to 0.7 MPa
Cooling water for thermal regulator (for Laser cooling)	Pressure : 0.2 to 0.5MPa
Dimentions	$1630^{W} \times 2345^{D} \times 2196^{H}$mm
Weight	2500kg